

ENGINEERING PRACTICES STUDY

PROJECT NUMBER: 5998-2008-028

TITLE:

Engineering Practices Study for Data Gathering for the purpose of Withdrawal of Adoption of
Non-Government Standard Test Methods for the Electrical Properties of Laminates

10 October 2008

FINAL REPORT

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ATTCH 1

I. OBJECTIVES: The objective of this study was to obtain from the military users either comments or concurrence on the proposed withdrawal of adoption of five non-Government standards (NGS) published by the IPC – Association Connecting Electronics Industries (IPC). The five NGS documents that were reviewed for withdrawal of adoption are listed in attachment 1.

II. BACKGROUND: The three NGS documents, IPC-TM-650 test methods, were referenced and used by MIL-S-13949 for evaluating the electrical properties of laminate materials used in the fabrication of printed wiring boards. The three NGS documents are no longer needed for DoD use since MIL-S-13949 has been canceled without replacement.

III. RESULTS: An electronic mail message survey was sent to 20 Department of Defense and Government activities asking for their input (comments or concurrence) concerning the withdrawal of the three NGS documents. All responses were in concurrence with the withdrawal of the three NGS documents. There were no negative or essential comments submitted.

IV. CONCLUSIONS: Based upon the fact that all responses were in concurrence with the withdrawal of the adoptions, notices should be prepared to withdraw the DoD adoption of the three NGS documents.

V. RECOMMENDATIONS: After this final report is coordinated with the activities that responded, DSCC-VAC will initiate standardization projects to prepare and issue notices of withdrawal for the three NGS documents.

Attachment for Project Number 5998-2008-028

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IPC-TM-650 Number	Rev	Title and URL	Date
2.5.1	B	Arc Resistance of Printed Wiring Material http://www.ipc.org/4.0_Knowledge/4.1_Standards/test/2.5.1b.pdf	05/86
2.5.5.2	A	Dielectric Constant and Dissipation Factor of Printed Wiring Board Material—Clip Method http://www.ipc.org/4.0_Knowledge/4.1_Standards/test/2.5.5.2a.pdf	12/87
2.5.6	B	Dielectric Breakdown of Rigid Printed Wiring Material http://www.ipc.org/4.0_Knowledge/4.1_Standards/test/2.5.6b.pdf	05/86